

Ablebond 789-3

Epoxy; Epoxide
Henkel Ablestik

Message:

ABLEBOND® 789-3™ die attach adhesive is designed for microelectronic applications. This adhesive exhibits strong adhesion to difficult-to-bond metals and retains its bond strength after exposure to moisture.

General Information		
Features	Bondability	
	Electrically Insulating	
	Moisture Resistant	
Uses	Adhesives	
Appearance	Amber	
Forms	Paste	
Thermal	Nominal Value	Unit
Glass Transition Temperature	126	°C
CLTE - Flow		
< 126°C	6.3E-5	cm/cm/°C
> 126°C	1.4E-4	cm/cm/°C
Thermal Conductivity (121°C)	0.30	W/m/K
Electrical	Nominal Value	Unit
Volume Resistivity	2.0E+14	ohms · cm
Dielectric Strength	31	kV/mm
Thermoset	Nominal Value	Unit
Pot Life (25°C)	130000	min
Shelf Life		
-40°C	52	wk
5°C	26	wk
Post Cure Time		
93°C	4.0	hr
150°C	0.50	hr
Fill Analysis	Nominal Value	Unit
Brookfield Viscosity - CP51 (25°C) ¹	36.5	Pa · s
Lap Shear		
Al to Al : 25°C	34.5	MPa
Au to Au : 25°C	37.9	MPa
Shear Strength - Die (Ceramic) ²	27.6	MPa
Weight Loss on Heating (250°C)	0.28	%
NOTE		

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|----|-----------------|
| 1. | Speed 5 rpm |
| 2. | 2 X 2 mm Si die |

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Recommended distributors for this material

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